TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSVI)

# 2SK3563

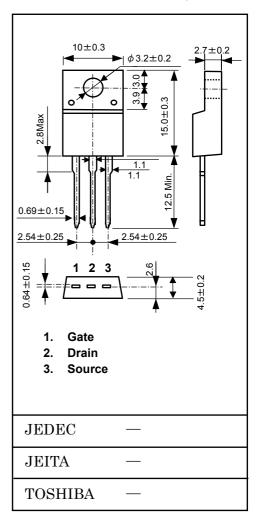
unit: mm

#### **Switching Regulator Applications**

- Low drain-source ON resistance: RDS (ON) =  $1.35 \Omega$  (typ.)
- High forward transfer admittance:  $|Y_{fs}| = 3.5S$  (typ.)
- Low leakage current: IDSS = 100  $\,\mu$  A (VDS = 500 V)
- Enhancement-mode:  $V_{th} = 2.0 \sim 4.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA)}$

### Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		$V_{DSS}$	500	V	
Drain-gate voltage (F	$R_{GS} = 20 \text{ k}\Omega$	$V_{DGR}$	500	V	
Gate-source voltage		V <sub>GSS</sub>	±30	V	
Drain current	DC (Note 1)	I <sub>D</sub>	5	A	
	Pulse (t = 1 ms) (Note 1)	I <sub>DP</sub>	20		
Drain power dissipati	on (Tc = 25°C)	P <sub>D</sub>	35	W	
Single pulse avalanc	he energy (Note 2)	E <sub>AS</sub>	180	mJ	
Avalanche current		I <sub>AR</sub>	5	Α	
Repetitive avalanche	energy (Note 3)	E <sub>AR</sub>	3.5	mJ	
Channel temperature	•	T <sub>ch</sub>	150	°C	
Storage temperature range		T <sub>stg</sub>	-55~150	°C	



#### **Thermal Characteristics**

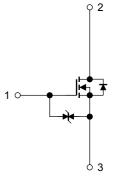
Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R <sub>th (ch-c)</sub>	3.57	°C/W
Thermal resistance, channel to ambient	R <sub>th (ch-a)</sub>	62.5	°C/W

Note 1: Please use devices on conditions that the channel temperature is below 150°C.

Note 2:  $V_{DD} = 90 \text{ V}$ ,  $T_{ch} = 25^{\circ}\text{C}$  (initial), L = 12.2 mH,  $I_{AR} = 5 \text{ A}$ ,  $R_G = 25 \Omega$ 

Note 3: Repetitive rating: Pulse width limited by maximum channel temperature

This transistor is an electrostatic sensitive device. Please handle with caution.



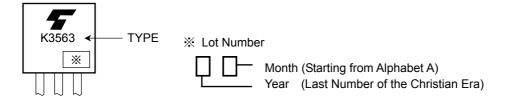
# **Electrical Characteristics (Ta = 25°C)**

Chara	acteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cur	rent	I <sub>GSS</sub>	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μΑ
Gate-source brea	kdown voltage	V (BR) GSS	$I_D = \pm 10 \; \mu A, \; V_{GS} = 0 \; V$	±30	_	_	V
Drain cut-off curre	ent	I <sub>DSS</sub>	V <sub>DS</sub> = 500 V, V <sub>GS</sub> = 0 V	_	_	100	μΑ
Drain-source brea	akdown voltage	V (BR) DSS	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	500	_	_	V
Gate threshold vo	oltage	V <sub>th</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	2.0	_	4.0	V
Drain-source ON	resistance	R <sub>DS</sub> (ON)	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 2.5 A		1.35	1.50	Ω
Forward transfer	admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 2.5 A	1.5	3.5	_	S
Input capacitance		C <sub>iss</sub>	V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V, f = 1 MHz		550	_	pF
Reverse transfer capacitance		C <sub>rss</sub>			7	_	
Output capacitance		Coss			70	_	
Switching time	Rise time	t <sub>r</sub>	$\begin{array}{c c} 10 \text{ V} & \text{ID} = 2.5 \text{ A} & \text{V}_{\text{OUT}} \\ VGS & & & & \\ 0 \text{ V} & & & & \\ 15 \Omega & & & & \\ & & & & & \\ & & & & & \\ & & & & $	_	10	_	
	Turn-on time	t <sub>on</sub>		_	20	_	no
	Fall time	t <sub>f</sub>			10	_	ns
	Turn-off time	t <sub>off</sub>	Duty $\leq$ 1%, $t_W = 10 \mu s$	_	50	_	
Total gate charge		Qg		_	16	_	
Gate-source charge		Q <sub>gs</sub>	$V_{DD} \simeq 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 5 \text{ A}$	_	10	_	nC
Gate-drain charge		Q <sub>gd</sub>		_	6		

# **Source-Drain Ratings and Characteristics (Ta = 25°C)**

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I <sub>DR</sub>	_	_	_	5	Α
Pulse drain reverse current (Note 1)	I <sub>DRP</sub>	_	_	_	20	Α
Forward voltage (diode)	V <sub>DSF</sub>	I <sub>DR</sub> = 5 A, V <sub>GS</sub> = 0 V	_	_	-1.7	V
Reverse recovery time	t <sub>rr</sub>	I <sub>DR</sub> = 5 A, V <sub>GS</sub> = 0 V,	_	1400	_	ns
Reverse recovery charge	Q <sub>rr</sub>	dl <sub>DR</sub> /dt = 100 A/μs	_	9	_	μС

### Marking



2 2003-01-27

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